



Product Information Sheet

EPO-TEK® P1011S-2

Date:	June 2025	Recommended Cure: Pre-Bake: 80°C/30 Minutes (maximum)+ Cure: 150°C/1 Hour (with or without vacuum)+ Post Cure: 285°C/90 Minutes
Rev:	I	
No. of Components:	Single	
Mix Ratio by Weight:	N/A	
Specific Gravity:		
Pot Life:	N/A	Dry Time: 7 Days
Shelf Life- Bulk:	One year refrigerated	

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

Product Description: EPO-TEK® P1011S-2 is a single component, modified polyimide, high temperature grade, silver-filled electrically conductive and thermally conductive adhesive designed for semiconductor die-attached and hybrid microelectronic packaging. It is a replacement for EPO-TEK® P1011S.

Typical Properties: Cure condition: Pre-Bake: 80°C/30 Minutes (maximum) - Cure: 150°C/1 Hour (with or without vacuum) – Post-Cure: 285°C/90 Minutes Different batches, conditions & applications yield differing results.

Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:

Color (before cure):	Dark Shiny Silver
Consistency:	Smooth Slightly Thixotropic Paste
Viscosity (23°C) @ 20 rpm:	10,130 cPs
Thixotropic Index:	2.60
Glass Transition Temp:	Not detected
Coefficient of Thermal Expansion (CTE):	
Below Tg:	
Above Tg:	
Shore D Hardness:	
Lap Shear @ 23°C:	
Die Shear @ 23°C:	Kg psi
Degradation Temp:	°C
Weight Loss:	
@ 200°C:	%
@ 250°C:	%
@ 300°C:	%
Suggested Operating Temperature:	< 300 °C (Intermittent)
Storage Modulus:	
Particle Size:	≤ 20 microns

ELECTRICAL AND THERMAL PROPERTIES:

Thermal Conductivity:	W/mK
Volume Resistivity @ 23°C:	0.00002 Ohm-cm

This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.

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